AXUS TECHNOLOGY

OnTrak Synergy™ and Integra™ Wafer and Substrate Cleaners

These scrubbers combine the successful principles of wafer cleaning established by OnTrak™ for optimized mechanical slurry particle removal plus metal contamination removal on post-CMP wafers and substrates using chemistries such as HF (optional). The product flow through these tools is linear and the wafers are kept wet throughout until the final drying process.

The OnTrak Synergy™

Post-CMP Double Sided Scrubber is designed to provide a platform for cleaning recipes that can incorporate a variety of chemical process combinations. The Synergy™ can also be used in applications such as MEMS and LEDs and is not limited only to Post-CMP cleaning. Through-the-brush chemical distribution, and bevel edge cleaning is included.

The OnTrak Integra™

Post-CMP Double Sided Scrubber uses the footprint, the components, and the successful cleaning technology of the Synergy™. This tool is designed to be integrated in the clean room with a Chemical-Mechanical Polishing tool for complete Dry In – Dry Out operation.

These tools provide distinct process modules including:

- Wet-station wafer loading; wafers in the queue are kept wet by a DI H_2O spray. A submergible bath is optional.
- Brush box #1 where the first mechanical-chemical cleaning step occurs using double sided PVA brushes and DI H_2O along with dilute cleaning chemistries such as ammonia.
- Brush box #2 which is identical to brush box #1 and where additional cleaning occurs (HF capable through the brushes).
- The SRD (Spin-Rinse-Dry) module is where the wafer is spun at 2000 rpm while it receives a final rinse. Drying occurs with the help of a nitrogen blow off and an infrared lamp. In addition, there is an optional Megasonics cleaning arm, and dilute chemistries can be dispensed before the spin action begins.
- A Mechanical Transfer Arm (robotic arm) transfers the clean and dry wafers to the output station.
- The Output Station has a unique indexer that reliably receives the clean dry wafer from the mechanical arm and places it down into the receive cassette where it is held in a vertical position until the run is completed.

Facilities

- Dimensions:
  Width:
    - Synergy 97” (2470mm)
    - Integra 72” (1829mm)
  Depth: 29” (737mm)
  Height: 59” (1499mm)
  Weight: < 2800 lbs.
- Electrical:
  110VAC, 1ph, 60 Hz, 20A
- DI Water Flow:
  Peak: 132 GPH
  Idle: 60 GPH
- Pressure:
  Nitrogen: 80-100psi
  CDA: 80-100 psi

About Axus Technology

Axus Technology delivers leading-edge CMP, wafer thinning and wafer polishing solutions for semiconductor, MEMS and substrate applications.

Axus Technology is the industry expert in providing material processing and CMP foundry services, process tools, and custom configured upgrades that are designed to meet your process and production requirements.

Customer support services include tool upgrades, spare parts, and field service support for a range of CMP and wafer grinding tools, including installed legacy tools.

For more information about contract refurbishment services, refurbished tools from Axus Technology, or field service for Strasbaugh tools, please contact either Tim St. Marie or Barrie VanDevender at our Chandler, AZ facility.